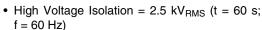


N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)}\left(\Omega\right)$	V _{GS} = 10 V	0.027		
Q _g (Max.) (nC)	95			
Q _{gs} (nC)	27			
Q _{gd} (nC)	46			
Configuration	Single			

FEATURES

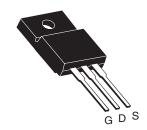
• Isolated Package

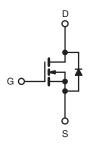




- Sink to Lead Creepage Distance = 4.8 mm
- 175 °C Operating Temperature
- · Dynamic dV/dt Rating
- · Low Thermal Resistance
- Lead (Pb)-free Available







N-Channel MOSFET

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	60	V
Gate-Source Voltage			V_{GS}	± 20	7
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C	- I _D	45	А
		T _C = 100 °C		30	
Pulsed Drain Current ^a			I_{DM}	220	
Linear Derating Factor				0.32	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	100	mJ
Maximum Power Dissipation	T _C =	: 25 °C	P _D	52	W
Peak Diode Recovery dV/dtc			dV/dt	4.5	V/ns
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 175	°C
Soldering Recommendations (Peak Temperature)	for 10 s			300 ^d	
Mounting Torque	6-32 or M3 screw			10	lbf ⋅ in
				1.1	N · m

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. $V_{DD}=25$ V, starting $T_J=25$ °C, L=129 $\mu H,~R_G=25$ $\Omega,~I_{AS}=30$ A (see fig. 12). c. $I_{SD}\leq 52$ A, $dI/dt\leq 250$ A/ $\mu s,~V_{DD}\leq V_{DS},~T_J\leq 175$ °C.
- d. 1.6 mm from case.



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	65	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	3.1	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	60	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.060	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		-	3.0	٧
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zeur Oete Veltere Dieie Oement		V _{DS} = 60 V, V _{GS} = 0 V		-	-	25	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 48 V	V _{DS} = 48 V, V _{GS} = 0 V, T _J = 150 °C		-	250	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 18 A ^b	-	0.027	-	Ω
Forward Transconductance	9 _{fs}	V _{DS} :	= 25 V, I _D = 18 A ^b	15	-	-	S
Dynamic				•	•		
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$		-	1500	-	pF
Output Capacitance	C _{oss}			-	720	-	
Reverse Transfer Capacitance	C _{rss}			-	100	-	
Drain to Sink Capacitance	С			-	12	-	•
Total Gate Charge	Qg		I _D = 52 A, V _{DS} = 48 V, see fig. 6 and 13 ^b	-	-	95	nC
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V		-	-	27	
Gate-Drain Charge	Q _{gd}	7		-	-	46	
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 30 \text{ V}, I_{D} = 52 \text{ A},$ $R_{G} = 9.1 \Omega, R_{D} = 0.54 \Omega,$ see fig. 10^{b}		-	19	-	- ns
Rise Time	t _r			-	120	-	
Turn-Off Delay Time	t _{d(off)}			-	55	-	
Fall Time	t _f			-	86	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	
Internal Source Inductance	L _S			-	7.5	-	- nH
Drain-Source Body Diode Characteristic	s			•	•	l.	
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	45	- A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	120	
Body Diode Voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 30 \text{A}, V_{GS} = 0 \text{V}^{\text{b}}$		-	-	2.5	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 52 A, dl/dt = 100 A/μs ^b		_	140	300	ns
Body Diode Reverse Recovery Charge	Q_{rr}				1.2	2.8	μC
Forward Turn-On Time	t _{on}	Intrinsic tu	ırn-on time is negligible (turn	-on is don	ninated by	L _S and I	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. Pulse width \leq 300 μ s; duty cycle \leq 2 %.

服务热线:400-655-8788



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

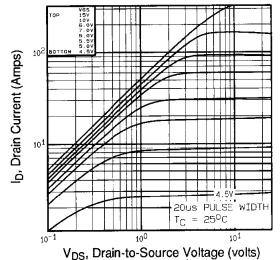


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

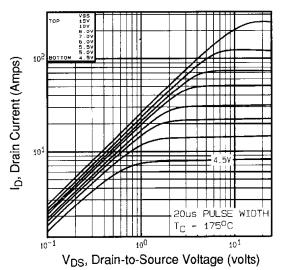


Fig. 2 - Typical Output Characteristics, $T_C = 175$ °C

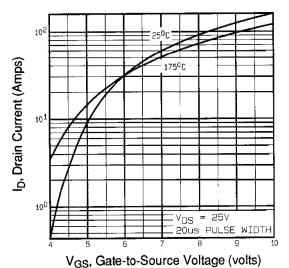


Fig. 3 - Typical Transfer Characteristics

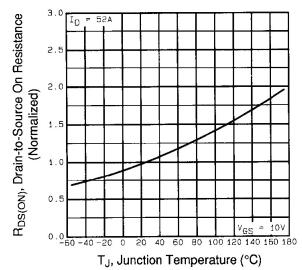


Fig. 4 - Normalized On-Resistance vs. Temperature



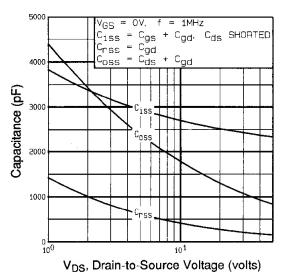


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

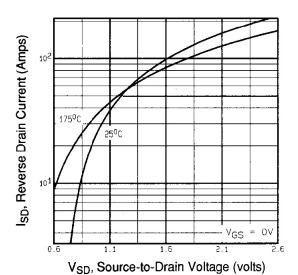


Fig. 7 - Typical Source-Drain Diode Forward Voltage

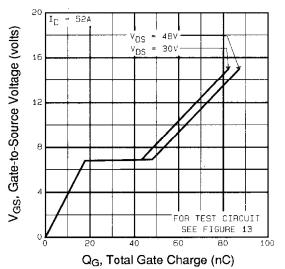
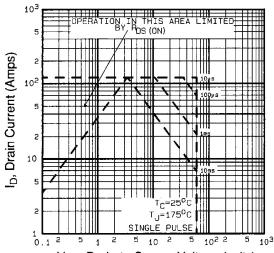


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



 V_{DS} , Drain-to-Source Voltage (volts) Fig. 8 - Maximum Safe Operating Area



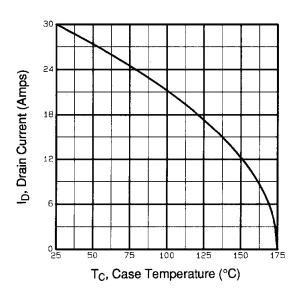


Fig. 9 - Maximum Drain Current vs. Case Temperature

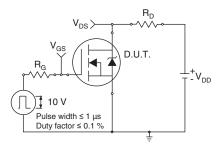


Fig. 10a - Switching Time Test Circuit

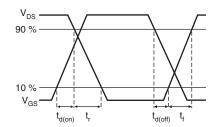


Fig. 10b - Switching Time Waveforms

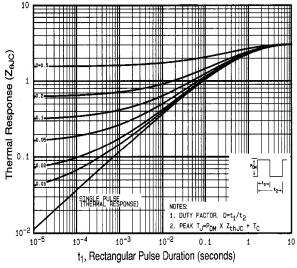


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

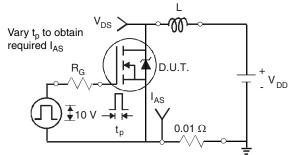


Fig. 12a - Unclamped Inductive Test Circuit

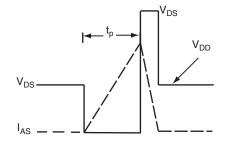
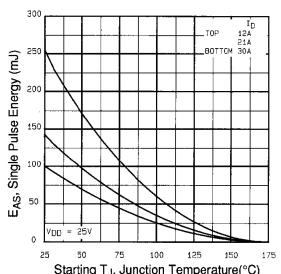


Fig. 12b - Unclamped Inductive Waveforms





 $Starting \ T_J, \ Junction \ Temperature (^{\circ}C)$ Fig. 12c - Maximum Avalanche Energy vs. Drain Current

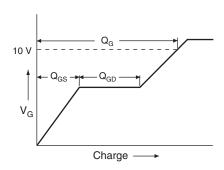


Fig. 13a - Basic Gate Charge Waveform

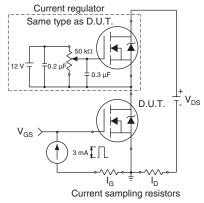
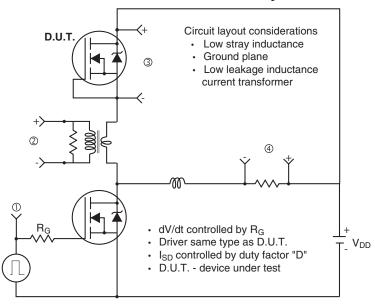


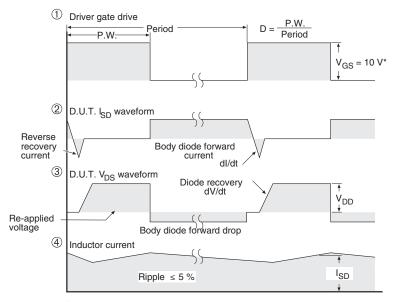
Fig. 13b - Gate Charge Test Circuit

服务热线:400-655-8788



Peak Diode Recovery dV/dt Test Circuit





* $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel

服务热线:400-655-8788



Disclaimer

All products due to improve reliability, function or design or for other reasons, product specifications and data are subject to change without notice.

Taiwan VBsemi Electronics Co., Ltd., branches, agents, employees, and all persons acting on its or their representatives (collectively, the "Taiwan VBsemi"), assumes no responsibility for any errors, inaccuracies or incomplete data contained in the table or any other any disclosure of any information related to the product.(www.VBsemi.com)

Taiwan VBsemi makes no guarantee, representation or warranty on the product for any particular purpose of any goods or continuous production. To the maximum extent permitted by applicable law on Taiwan VBsemi relinquished: (1) any application and all liability arising out of or use of any products; (2) any and all liability, including but not limited to special, consequential damages or incidental; (3) any and all implied warranties, including a particular purpose, non-infringement and merchantability guarantee.

Statement on certain types of applications are based on knowledge of the product is often used in a typical application of the general product VBsemi Taiwan demand that the Taiwan VBsemi of. Statement on whether the product is suitable for a particular application is non-binding. It is the customer's responsibility to verify specific product features in the products described in the specification is appropriate for use in a particular application. Parameter data sheets and technical specifications can be provided may vary depending on the application and performance over time. All operating parameters, including typical parameters must be made by customer's technical experts validated for each customer application. Product specifications do not expand or modify Taiwan VBsemi purchasing terms and conditions, including but not limited to warranty herein.

Unless expressly stated in writing, Taiwan VBsemi products are not intended for use in medical, life saving, or life sustaining applications or any other application. Wherein VBsemi product failure could lead to personal injury or death, use or sale of products used in Taiwan VBsemi such applications using client did not express their own risk. Contact your authorized Taiwan VBsemi people who are related to product design applications and other terms and conditions in writing.

The information provided in this document and the company's products without a license, express or implied, by estoppel or otherwise, to any intellectual property rights granted to the VBsemi act or document. Product names and trademarks referred to herein are trademarks of their respective representatives will be all.

Material Category Policy

Taiwan VBsemi Electronics Co., Ltd., hereby certify that all of the products are determined to be oHS compliant and meets the definition of restrictions under Directive of the European Parliament 2011/65 / EU, 2011 Nian. 6. 8 Ri Yue restrict the use of certain hazardous substances in electrical and electronic equipment (EEE) - modification, unless otherwise specified as inconsistent.(www.VBsemi.com)

Please note that some documents may still refer to Taiwan VBsemi RoHS Directive 2002/95 / EC. We confirm that all products identified as consistent with the Directive 2002/95 / EC European Directive 2011/65 /.

Taiwan VBsemi Electronics Co., Ltd. hereby certify that all of its products comply identified as halogen-free halogen-free standards required by the JEDEC JS709A. Please note that some Taiwanese VBsemi documents still refer to the definition of IEC 61249-2-21, and we are sure that all products conform to confirm compliance with IEC 61249-2-21 standard level JS709A.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by VBsemi Elec manufacturer:

Other Similar products are found below:

IRFD120 JANTX2N5237 BUK455-60A/B MIC4420CM-TR VN1206L NDP4060 SI4482DY IPS70R2K0CEAKMA1 SQD23N06-31L-GE3
TK16J60W,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 DMN1053UCP4-7 SQJ469EP-T1-GE3 NTE2384 DMC2700UDMQ-7
DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP BXP7N65D BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L
BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
BSO203SP BSO211P IPA60R230P6 IPA60R460CE